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USE OF CHIP-ON-BOARD TECHNOLOGY TO MOUNT OPTICAL TRANSMITTING  
AND DETECTING DEVICES WITH A PROTECTIVE COVERING WITH MULTIPLE  
5 OPTICAL INTERFACE OPTIONS

ABSTRACT OF THE DISCLOSURE

A packaging system for optoelectronic devices that does not  
require the optoelectronic device to be hermetically sealed,  
10 whereby the optoelectronic device is mounted directly on a  
substrate, allowing for high-speed trace designs up to the die  
for excellent high speed signal integrity and EMI performance.

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